

**PRODUCT DESCRIPTION**

PUR 6649 provides the following product characteristics:

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|-------------------|-------------------------------|
| Technology | Polyurethane Hot Melt |
| Appearance | Light yellow to amber solid |
| Solids Content, % | 100 |
| Components | One part - requires no mixing |
| Cure | Solidification and Moisture |
| Application | Device assembly |

PUR 6649 is a reactive hotmelt adhesive formulated to cure with moisture. This material is pressure sensitive, providing instant high initial strength and fast speed of set.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Viscosity, Brookfield - Thermosel, 100 °C, mPa-s (cP):

Spindle 27 6,750

Density @ 25°C ±0.05, g/cm³ 1.1

Shelf Life @ 5 to 25°C (from date of manufacture), days 365

Flash Point - See SDS

TYPICAL CURING PERFORMANCE

Open Time @ 25 °C, minute ~1

Preheating Schedule 20 to 30 mins @ 100°C

Application Temperature, °C 90 to 110

Open time is the bonding range of a 1 mm bead of molten adhesive on substrate. It is based on room temperature environment. Higher temperature will lengthen the open time while lower environmental temperatures will shorten the open time.

PUR 6649 cures exclusively by moisture and gains its final strength in 1-5 days. This material, however, exhibits high handling strength instantly after bonding.

Curing is a chemical reaction depending on the following parameters:

- Humidity in the rooms of application and storage
- Moisture content on the substrates
- Permeability of the substrates to be bonded
- Application volume / layer of the adhesive film

The above cure profile is a guideline recommendation. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

GENERAL INFORMATION

For safe handling information on this product, consult the Safety Data Sheet.

Pretreatment:

1. The bonding surfaces must be clean, dry and free of oil and grease.
2. Substrate temperature should not fall below 20°C during application.
3. Lower temperatures will lead to early solidification of the adhesive and to a reduced open time, the adhesive might even flake off.
4. The substrates may be preheated if necessary.

Application:

1. PUR 6649 can be applied from heating cartridge guns, from usual syringe type melting equipment.
2. At longer rest periods, melting and application temperatures should be decreased. Longer exposure to higher temperatures can lead to a viscosity increase.

STORAGE:

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage : 5 to 25 °C

Material removed from containers may be contaminated during use. Do not return product to the original container. Longain Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.